

Data Sheet January 2000 File Number 3693.2

# 15A, 1000V Hyperfast Dual Diode

The RHRG15100CC is a hyperfast dual diode with soft recovery characteristics ( $t_{rr}$  < 60ns). It has half the recovery time of ultrafast diodes and is of silicon nitride passivated ion-implanted epitaxial planar construction.

This device is intended for use as a freewheeling/clamping diode and rectifier in a variety of switching power supplies and other power switching applications. Its low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits, thus reducing power loss in the switching transistors.

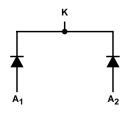
Formerly developmental type TA49062.

# **Ordering Information**

PART NUMBER	PACKAGE	BRAND
RHRG15100CC	TO-247	RHR15100C

NOTE: When ordering, use the entire part number.

# Symbol



#### **Features**

•	Hyperfast with Soft Recovery < 60ns
•	Operating Temperature
•	Reverse Voltage

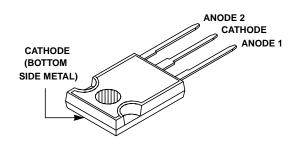
- · Avalanche Energy Rated
- Planar Construction

# **Applications**

- · Switching Power Supplies
- · Power Switching Circuits
- · General Purpose

### **Packaging**

**JEDEC STYLE TO-247** 



#### **Absolute Maximum Ratings** (Per Leg) $T_C = 25^{\circ}C$ , Unless Otherwise Specified

	RHRG15100CC	UNITS
Peak Repetitive Reverse VoltageV <sub>RRM</sub>	1000	V
Working Peak Reverse Voltage	1000	V
DC Blocking VoltageV <sub>R</sub>	1000	V
Average Rectified Forward Current $I_{F(AV)}$ ( $T_C = 130^{\circ}C$ )	15	Α
Repetitive Peak Surge Current	30	Α
Nonrepetitive Peak Surge Current	200	Α
Maximum Power Dissipation	100	W
Avalanche Energy (See Figures 10 and 11)	20	mJ
Operating and Storage Temperature	-65 to 175	οС

**Electrical Specifications** (Per Leg) T<sub>C</sub> = 25°C, Unless Otherwise Specified

SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
V <sub>F</sub>	I <sub>F</sub> = 15A	-	-	3.0	V
	I <sub>F</sub> = 15A, T <sub>C</sub> = 150°C	-	-	2.5	V
I <sub>R</sub>	V <sub>R</sub> = 1000V	-	-	100	μΑ
	$V_R = 1000V, T_C = 150^{\circ}C$	-	-	500	μΑ
t <sub>rr</sub>	I <sub>F</sub> = 1A, dI <sub>F</sub> /dt = 100A/μs	-	-	60	ns
	$I_F = 15A$ , $dI_F/dt = 100A/\mu s$	-	-	70	ns
t <sub>a</sub>	I <sub>F</sub> = 15A, dI <sub>F</sub> /dt = 100A/μs	-	40	-	ns
t <sub>b</sub>	$I_F = 15A$ , $dI_F/dt = 100A/\mu s$	-	25	-	ns
Q <sub>RR</sub>	I <sub>F</sub> = 15A, dI <sub>F</sub> /dt = 100A/μs	-	160	-	nC
СЈ	V <sub>R</sub> = 10V, I <sub>F</sub> = 0A	-	66	-	pF
$R_{ heta JC}$		-	-	1.5	°C/W

#### **DEFINITIONS**

 $V_F$  = Instantaneous forward voltage (pw = 300 $\mu$ s, D = 2%).

I<sub>R</sub> = Instantaneous reverse current.

 $t_{rr}$  = Reverse recovery time (Figure 9), summation of  $t_a$  +  $t_b$ .

 $t_a$  = Time to reach peak reverse current (See Figure 9).

 $t_b$  = Time from peak  $I_{RM}$  to projected zero crossing of  $I_{RM}$  based on a straight line from peak  $I_{RM}$  through 25% of  $I_{RM}$  (See Figure 9).

 $Q_{RR}$  = Reverse recovery charge.

 $C_J$  = Junction Capacitance.

 $R_{\theta JC}$  = Thermal resistance junction to case.

pw = pulse width.

D = duty cycle.

# **Typical Performance Curves**

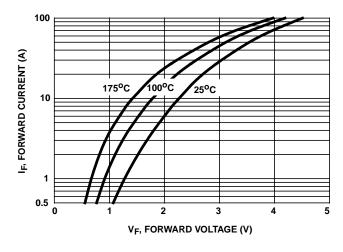


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

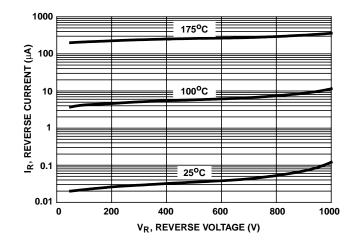


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

# Typical Performance Curves (Continued)

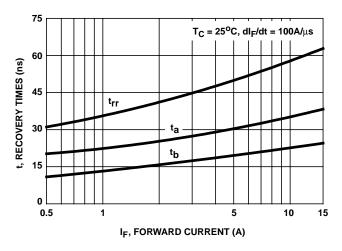


FIGURE 3.  $t_{rr}$ ,  $t_a$  AND  $t_b$  CURVES vs FORWARD CURRENT

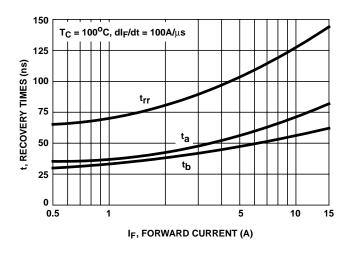


FIGURE 4. t<sub>rr</sub>, t<sub>a</sub> AND t<sub>b</sub> CURVES vs FORWARD CURRENT

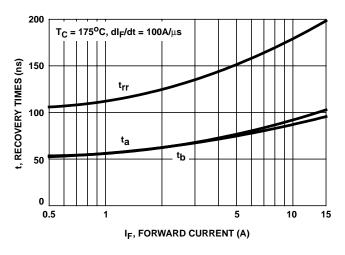


FIGURE 5. t<sub>rr</sub>, t<sub>a</sub> AND t<sub>b</sub> CURVES vs FORWARD CURRENT

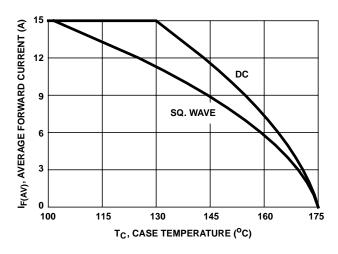


FIGURE 6. CURRENT DERATING CURVE

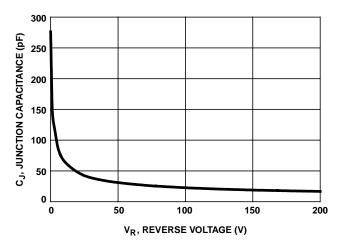


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

#### Test Circuits and Waveforms

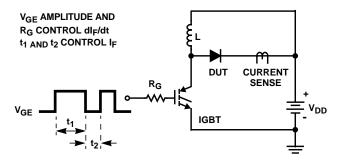


FIGURE 8. t<sub>rr</sub> TEST CIRCUIT

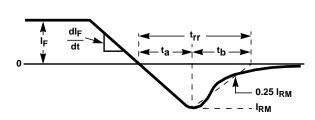


FIGURE 9. t<sub>rr</sub> WAVEFORMS AND DEFINITIONS

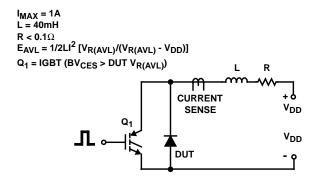


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

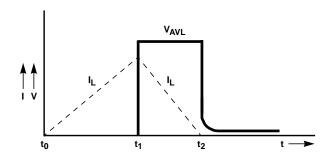


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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